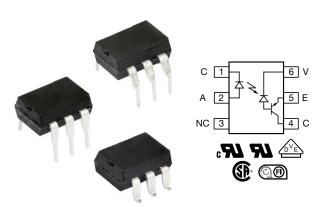


High Speed Optocoupler, 1 MBd, Transistor Output



ADDITIONAL RESOURCES







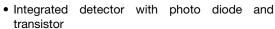
DESCRIPTION

The SFH636 is an optocoupler with a GaAlAs infrared emitting diode, optically coupled to an integrated photo detector consisting of a photo diode and a high speed transistor in a low pinout DIP-6 package. The device is functionally similar to 6N136 except there is no base connection and the foot print is different. Noise and common mode rejection performance is enhanced by not bringing out the base connection.

Signals can be transmitted between two electrically separated circuits up to frequencies of 2 MHz.

FEATURES

- High CMR of 10 kV/µs
- · High speed optocoupler without base connection





 TTL compatible Guaranteed DC performance overtemperature: 0 °C to 70 °C

RoHS COMPLIANT

- Open collector output
- Supply voltage up to 30 V
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- · Data communications
- Programmable controllers
- IGBT logic and MOSFET driver stages
- IPM drivers

AGENCY APPROVALS

- UL1577
- cUL
- DIN EN 60747-5-5 (VDE 0884-5) available with option 1
- CSA
- FIMKO

ORDERING INFORMATION					
S F H 6 PART NUMBER	3 6 - X 0 # # T PACKAGE OPTION TAPE AND REEL Option 7 > 00				
AGENCY CERTIFIED/PACKAGE	CTR (%)				
UL	≥ 19				
DIP-6	SFH636				
SMD-6, option 7	SFH636-X007T				
VDE, UL	≥ 19				
DIP-6	SFH636-X001				
DIP-6, option 6	SFH636-X016				
SMD-6, option 7	SFH636-X017T				

Note

· Additional options may be possible, please contact sales office



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ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)								
PARAMETER	CONDITIONS	SYMBOL	VALUE	UNIT				
INPUT								
Reverse voltage		V_R	3.0	V				
DC forward current		I _F	25	mA				
Surge forward current	$t_P \le 1.0 \ \mu s$, 300 pulses/s	I _{FSM}	1.0	Α				
Power dissipation		P _{diss}	45	mW				
OUTPUT								
Supply voltage		Vs	-0.5 to +30	V				
Output voltage		V _O	-0.5 to +20	V				
Output current		Ιο	8	mA				
Power dissipation		P _{diss}	100	mW				
COUPLER								
Storage temperature range		T _{stg}	-55 to +150	°C				
Ambient temperature range		T _{amb}	-55 to +100	°C				
Junction temperature		Tj	100	°C				
Soldering temperature	Max. 10 s, dip soldering: distance to seating plane ≥ 1.5 mm	T _{sld}	260	°C				
Power dissipation		P _{diss}	145	mW				

Note

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not
implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute
maximum ratings for extended periods of the time can adversely affect reliability

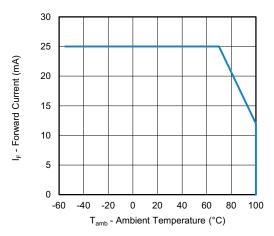


Fig. 1 - Forward Current vs. Ambient Temperature

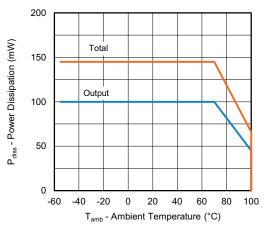


Fig. 2 - Power Dissipation vs. Ambient Temperature

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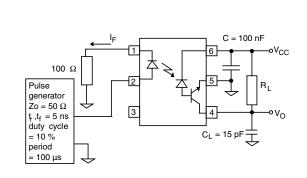
Vishay Semiconductors

ELECTRICAL CHARACTERISTICS (T _{amb} = 0 °C to 70 °C; typical values are at T _{amb} = 25 °C)								
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT		
INPUT								
Forward voltage	I _F = 16 mA	V_{F}	-	1.3	1.8	V		
Reverse current	V _R = 3 V	I_R	ı	0.5	10	μΑ		
Input capacitance	$V_R = 0 V$, $f = 1 MHz$	C _{IN}	1	20	-	pF		
OUTPUT	OUTPUT							
Low level supply current	$I_F = 16 \text{ mA}, V_O = \text{open}, V_{CC} = 15 \text{ V}$	I _{CCL}	ı	150	-	μΑ		
High level supply current	$I_F = 0 \text{ V}, V_O = \text{open}, V_{CC} = 15 \text{ V}^{(1)}$	I _{CCH}	1	0.01	1	μΑ		
Trigit level supply current	$I_F = 0 \text{ V}, V_O = \text{open}, V_{CC} = 15 \text{ V}$	I _{CCH}	-	0.01	2	μΑ		
	$I_F = 0 \text{ V}, V_O = \text{open}, V_{CC} = 5.5 \text{ V}^{(1)}$	I _{OH}	-	0.001	0.5	μΑ		
High level output current	$I_F = 0 \text{ V}, V_O = \text{open}, V_{CC} = 15 \text{ V}^{(1)}$	I _{OH}	1	0.001	1	μΑ		
	$I_F = 0 \text{ V}, V_O = \text{open}, V_{CC} = 15 \text{ V}$	I _{OH}	-		50	μΑ		
Collector emitter capacitance V _{CE} = 5 V, f = 1 MHz		C _{CE}	-	3	-	pF		
COUPLER								
Coupling capacitance		C _{IO}	-	0.6	-	pF		
Collector emitter saturation voltage	$I_F = 16$ mA, $I_O = 2.4$ mA, $V_{CC} = 4.5$ V $^{(1)}$	V _{OL}	-	0.1	0.4	V		

Notes

 Minimum and maximum values are testing requirements. Typical values are characteristics of the device and are the result of engineering evaluation. Typical values are for information only and are not part of the testing requirements

 $^{^{(1)}}$ $T_{amb} = 25$ $^{\circ}C$



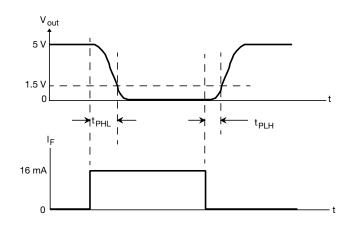


Fig. 3 - Test Setup

Fig. 4 - Switching Time Measurement

CURRENT TRANSFER RATIO (T _{amb} = 0 °C to 70 °C; typical values are at T _{amb} = 25 °C)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
1.7	$I_F = 16 \text{ mA}, V_O = 0.4 \text{ V}, V_{CC} = 4.5 \text{ V}$ (1)	CTR	19	30	-	%
I _C /I _F	$I_F = 16 \text{ mA}, V_O = 0.5 \text{ V}, V_{CC} = 4.5 \text{ V}$	CTR	15	-	-	%

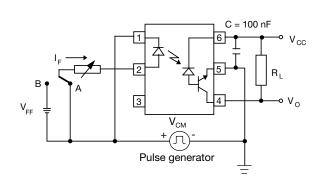
Note

isfh636_01

 $^{(1)}$ $T_{amb} = 25~^{\circ}C$

SWITCHING CHARACTERISTICS (T _{amb} = 25 °C)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Propagation delay time (high to low)	$I_F = 16 \text{ mA}, V_{CC} = 5.0 \text{ V}, R_L = 1.9 \text{ k}\Omega$	t _{PHL}	ı	ı	0.8	μs
Propagation delay time (low to low)	$I_F = 16 \text{ mA}, V_{CC} = 5.0 \text{ V}, R_L = 1.9 \text{ k}\Omega$	t _{PLH}	-	-	0.8	μs





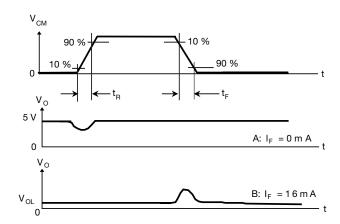


Fig. 5 - Common Mode Transient Test

Fig. 6 - Measurement Waveform of CMR

COMMON MODE TRANSIENT IMMUNITY ($T_{amb} = 25 ^{\circ}C$)							
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT	
Common mode transient immunity (high)	$I_F = 0$ mA, $V_{CM} = 1500 V_{PP}$, $R_L = 1.9 \text{ k}\Omega$, $V_{CC} = 5.0 \text{ V}$	CM _H	-	10 000	-	V/µs	
Common mode transient immunity (low)	I_F = 16 mA, V_{CM} = 1500 V_{PP} , R_L = 1.9 k Ω , V_{CC} = 5.0 V	CM _L	-	10 000	=	V/µs	

SAFETY AND INSULATION RATINGS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	RAMETER TEST CONDITION		VALUE	UNIT		
Climatic classification	According to IEC 68 part 1		55/100/21			
Pollution degree	According to DIN VDE 0109		2			
Comparative tracking index	Insulation group IIIa	CTI	175			
Maximum rated withstanding isolation voltage	According to UL1577, t = 1 min	V _{ISO}	4420	V_{RMS}		
Tested withstanding isolation voltage	According to UL1577, t = 1 s	V _{ISO}	5300	V_{RMS}		
Maximum transient isolation voltage	According to DIN EN 60747-5-5	V_{IOTM}	8000	V _{peak}		
Maximum repetitive peak isolation voltage	According to DIN EN 60747-5-5	V_{IORM}	890	V _{peak}		
Isolation resistance	$T_{amb} = 25 ^{\circ}C, V_{IO} = 500 V$	R _{IO}	≥ 10 ¹²	Ω		
isolation resistance	T _{amb} = 100 °C, V _{IO} = 500 V	R _{IO}	≥ 10 ¹¹	Ω		
Output safety power		P _{SO}	700	mW		
Input safety current		I _{SI}	400	mA		
Input safety temperature		T _S	175	°C		
Creepage distance	DIP-6		≥ 7	mm		
Clearance distance	DIP-6		≥ 7	mm		
Creepage distance	DIP-6, option 6		≥8	mm		
Clearance distance	DIP-6, option 6		≥8	mm		
Creepage distance	SMD-6, option 7		≥ 7	mm		
Clearance distance	SMD-6, option 7		≥ 7	mm		
Insulation thickness		DTI	≥ 0.4	mm		

Note

• As per IEC 60747-5-5, § 7.4.3.8.2, this optocoupler is suitable for "safe electrical insulation" only within the safety ratings. Compliance with the safety ratings shall be ensured by means of protective circuits

TYPICAL CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

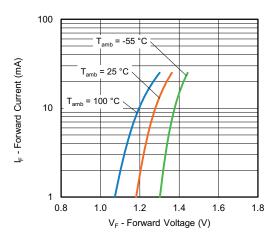


Fig. 7 - Forward Current vs. Forward Voltage

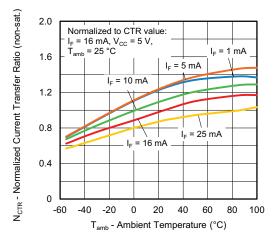


Fig. 8 - Normalized Current Transfer Ratio (non-sat.) vs.
Ambient Temperature

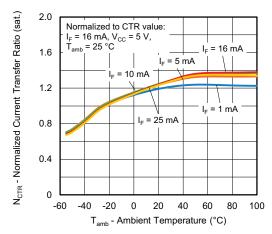


Fig. 9 - Normalized Current Transfer Ratio (sat.) vs.
Ambient Temperature

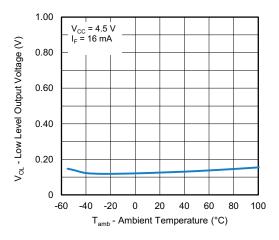


Fig. 10 - Low Level Output Voltage vs. Ambient Temperature

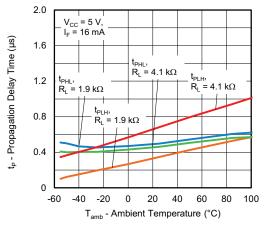
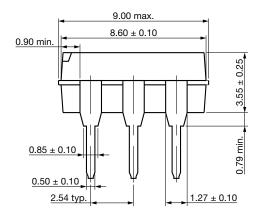
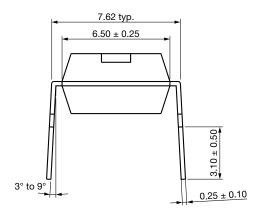


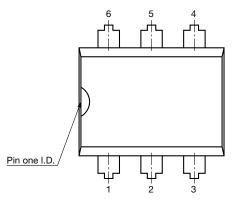
Fig. 11 - Propagation Delay Time vs. Ambient Temperature

PACKAGE DIMENSIONS

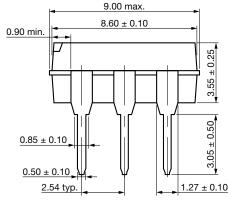
DIP-6

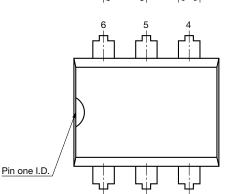


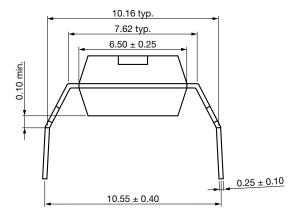




DIP-6, Option 6

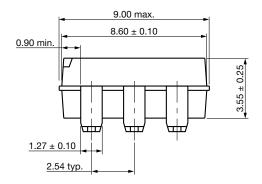


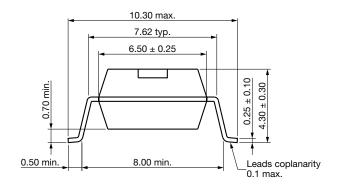


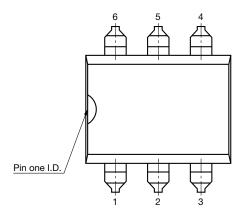


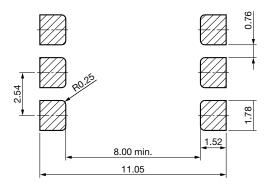
Rev. 1.9, 30-Sep-2019 6 Document Number: 83681

SMD-6, Option 7









PACKAGE MARKING



Fig. 12 - Example of SFH636



Fig. 13 - Example of SFH636-X017T

Notes

- VDE logo is only marked on option 1 parts
- Tape and reel suffix (T) is not part of the package marking

PACKING INFORMATION (in millimeters)

Tube

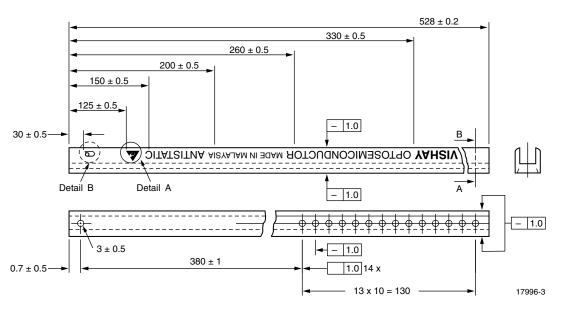


Fig. 14 - Shipping Tube Specifications for DIP-6 Packages

DEVICES PER TUBS					
TYPE	UNITS/TUBE	TUBES/BOX	UNITS/BOX		
DIP-6	50	40	2000		
DIP-6, option 6	50	40	2000		

DIP-6

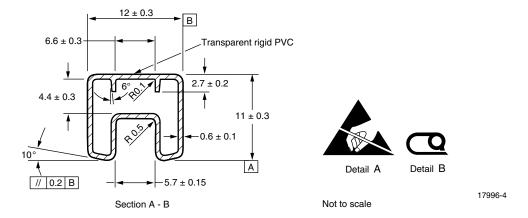


Fig. 15 - Tube Shipping Medium

DIP-6, Option 6

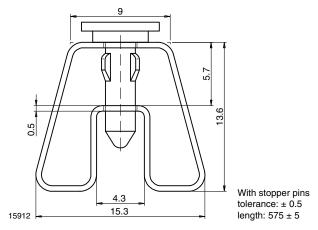


Fig. 16 - Tube Shipping Medium

Tape and Reel

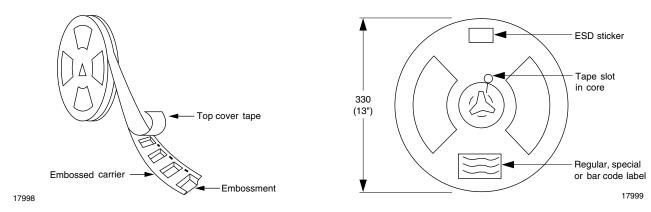


Fig. 17 - Tape and Reel Shipping Medium

Fig. 18 - Tape and Reel Shipping Medium

SMD-6, Option 7

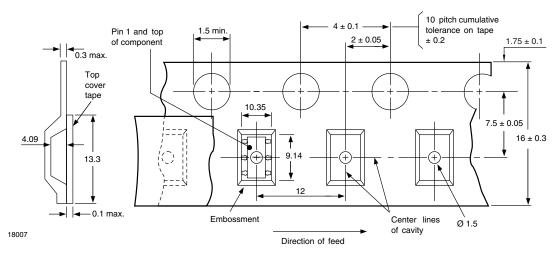


Fig. 19 - Tape and Reel Packing (1000 pieces on Reel)



SOLDER PROFILES

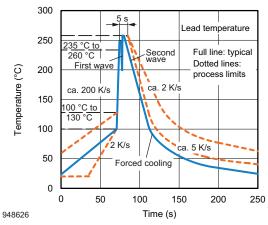


Fig. 20 - Wave Soldering Double Wave Profile According to J.STD-020 for DIP Devices

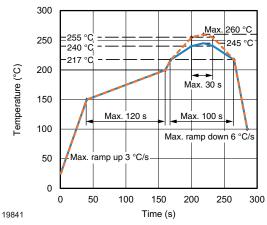


Fig. 21 - Lead (Pb)-free Reflow Solder Profile According to J-STD-020 for SMD Devices

HANDLING AND STORAGE CONDITIONS

ESD level: HBM class 2 Floor life: unlimited

Conditions: T_{amb} < 30 °C, RH < 85 %

Moisture sensitivity level 1, according to J-STD-020

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